

# ISMP 2015

14<sup>th</sup> International Symposium  
on Microelectronics and Packaging

October 13(Tue) -15(Thu), 2015  
KINTEX Hall2, Seoul / Ilsan, Korea

<http://ismp2015.kmeps.or.kr>



Organized by :  The Korean Microelectronics and Packaging Society  
Supported by : Korea Semiconductor Industry Association

# ISMP 2015

<http://ismp2015.kmeps.or.kr>

14<sup>th</sup> International Symposium on Microelectronics and Packaging

October 13(Tue)-15(Thu), 2015 KINTEX Hall2, Seoul / Ilsan, Korea

## INVITATION

It is our pleasure to announce that the 14th International Symposium on Microelectronics and Packaging (ISMP 2015) will be held at KINTEX (Korea International Exhibition Center) convention center located at Seoul/Ilsan Korea during October 13-15 2015. This international conference is organized by KMEPS (the Korean Microelectronics and Packaging Society), and will address comprehensive coverage of recent advances in Materials, Processing, Simulation, Printed Electronics, Nano/Micro Joining Technology and Reliability of Electronic Packaging. The technical sessions for oral and poster presentations will be in parallel with the 17th International Semiconductor Exhibition (<http://www.sedex.org>) at KINTEX. The ISMP 2015 will provide an excellent opportunity for scientists and engineers of academic institutes and industries to discuss recent advances in electronic packaging technology and forecast new technological directions. We cordially invite you to submit abstracts for the conference, and look forward to welcoming you in Seoul, Korea.

General Chairman of ISMP 2015, Ho Jung Chang, Ph.D

## SYMPOSIUM TOPICS

ISMP 2015 will include all fundamental and applied sciences and technologies related to the fields of electronic materials, devices, and packagings. Topics may include from, but are not limited to, the following areas:

- Electronic Materials and Processing
- Optoelectronic and Photonic Materials and Processing
- Advanced Packaging Technologies
- 3D Integration and Packaging
- LED Packaging and Applications
- MEMS Packaging and Applications
- Modeling, Simulation, Quality and Reliability of Electronic Components
- Nanomaterials and its Application Technology
- Micro/Nano Joining Technology
- Interconnection Materials and its Reliability
- IoT (Internet of Things), Sensor Devices and System
- Soldering and Surface Mount Technology
- Wearable and Stretchable Electronics
- Printed Electronics and Materials

# ISMP 2015

<http://ismp2015.kmeps.or.kr>

14<sup>th</sup> International Symposium on Microelectronics and Packaging

October 13(Tue)-15(Thu), 2015 KINTEX Hall2, Seoul / Ilsan, Korea

## SPEAKERS (As of Mar. 31<sup>th</sup>, 2015)

### Plenary Speakers



Choon Heung Lee  
(President of AMKOR, Korea)



William Chen  
(ASE, Taiwan)

### Keynote Speakers



Akio Hirose  
(Osaka University, Japan)



Bill Bader  
(President of iNEMI, USA)



Rolf Aschenbrenner  
(IZM Fraunhofer, Germany)



Chunqing Wang, China  
(Harbin Institute of Technology)

### Invited Speakers



N. N. Ekere  
(Univ. of Wolverhampton, UK)



Mustafa Yavuz  
(Univ. of Waterloo, Canada)

## ABSTRACT SUBMISSION

You are invited to submit a 300-word abstract through the email ([kmeps@kmeps.or.kr](mailto:kmeps@kmeps.or.kr)) including title, authors, affiliations, address and corresponding author (refer to abstract template) by May 31, 2015 for oral and poster presentations. Acknowledgement of your abstract submission will be sent to the presenting/corresponding authors' email addresses by July 15, 2015.

## PAPER PUBLICATION

Authors whose abstracts are accepted will be requested to submit full manuscript by August 15, 2015 (Manuscript submission is not mandatory). After peer review, all accepted papers will be published in following several leading SCI(E) and KCI journals.

- Soldering and Surface Mount Technology (SCIE) /
- Materials Transactions (SCI) / · Journal of Nanoelectronics and Optoelectronics (SCIE)
- Nanoscience and Nanotechnology Letters (SCIE) / · Journal of Microelectronics and Packaging Society (KCI)

# ISMP 2015

14<sup>th</sup> International Symposium on Microelectronics and Packaging  
October 13(Tue)-15(Thu), 2015 KINTEX Hall2, Seoul / Ilsan, Korea

## ORGANIZING COMMITTEE

### Honorary Chairmen

Se-Yong Oh (SK Hynix)  
Jin Yu (Korea Advanced Institute of Science and Technology)  
Young-Ho Kim (Hanyang University)  
Chang-Ho Choi (HANA Micron Inc.)

### International Honorary Co-chairmen

Hagime Tomokake (Fukuoka University)  
Akio Hirose (Osaka University)  
Chunqing Wang (Harbin Institute of Technology)

### General Chairman

Ho Jung Chang (Dankook University)

### General Co-Chairmen

Kyung-Wook Paik (Korea Advanced Institute of Science and Technology)  
Young Jae Kim (Daeduck Electronics Co., Ltd.)  
Choon-Heung Lee (Amkor Korea)  
Jin-Ho Ahn (Hanyang University)

### International Advisory Committee

**Chairman** : Tae Sung Oh (Hongik University)  
**Co-chairman** : Yong Bin Sun (Kyonggi University)  
: Yasumitsu Orii (IBM Japan, Ltd.)  
: Sung Yi (Portland State University)  
: Mustafa Yavuz (University of Waterloo)  
: N. N. Ekere (Wolverhampton University)  
: G. P. Li (University of California, Irvine)  
: Carlos Moraes (University of Unisinos)  
: S.W. Ricky Lee (Hong Kong University of Science & Technology)

Sa-Yoon Kang (Samsung Electronics Co., Ltd.)  
Namsuk Kim (SK Hynix)  
Hsiang-Chen Hsu (I-Shou University)  
Charles E. Bauer (Tech Lead Corp.)  
C. Robert Kao (National Taiwan University)  
Yu-Jung Huang (I-Shou University)  
Yang Ju (Nagoya University)  
Tae-Kyu Lee (Cisco Systems)  
Kwang-Lung Lin (National Cheng Kung University)  
Ming-Yi Tsai (Chang Gung University)  
Choong-Un Kim (University of Texas at Arlington)  
Youngsuk Kim (Tokyo Institute of Technology)  
Kang-Wook Lee (Tohoku University)

### Local Organizing Committee:

**Chairman** : Jae-Ho Lee (Hongik University)  
**Co-chairman** : Nam-Kee Kang (Korea Electronics Technology Institute)  
: Sung-Hoon Choa (Seoul National University of Science and Technology)

Sungdong Kim (Seoul National University of Science and Technology)  
Young-Joo Ko (Daeduck Electronics Co., Ltd.)  
U. Bae (ASE Korea, Inc.)  
Jong-Hun Kim (Nepes corp.)  
Sang-Young Park (EO Technics Co., Ltd.)  
Tae-Koo Lee (Korea Circuit Co., Ltd.)  
Ki-Do Chun (LG Innotek Co., Ltd.)  
Young-Soo Kim (Signetics Corp.)  
Dong-Ki Nam (Doosan Corporation Electro-Materials)  
Jong-Tae Moon (Hojeonable Inc.)  
Won-Sun Shin (ASE Korea, Inc.)  
Billy Ahn (STATSChipPAC Korea.)  
Keum-Sool Oh (Duksan Hi-Metal Co., Ltd.)

### Program Committee

**Chairman** : Gu Sung Kim (Kangnam University)  
**Co-chairman**  
: Jong Chul Park (Korea Electronics Technology Institute)  
: Sehoon Yoo (Korea Institute of Industrial Technology)

Yeong K. Kim (Inha University)  
Sarah Eunkyung Kim (Seoul National University of Science and Technology)  
Kwang-Sung Choi (Electronics and Telecommunications Research Institute)

### Publication Committee

**Chairman** : Seung-Boo Jung (Sungkyunkwan University)  
**Co-chairman** : Young-Bae Park (Andong National University)  
: Myung-Yung Jeong (Pusan National University)

Tomokazu Sano (Osaka University)  
Dae-Ihl Kwon (Ulsan National Institute of Science and Technology)  
Taek-Soo Kim (Korea Advanced Institute of Science and Technology)  
Hyung-Ho Park (Yonsei University)  
Jong-Woong Kim (Korea Electronics Technology Institute)

### Financial Committee

**Chairman** : Young Chang Joo (Seoul National University)  
**Co-chairman** : Hyouk Lee (Sunmoon University)

Jong-Hyun Lee (Seoul National University of Science and Technology)  
Kwang-Joo Lee (LG Chem.)  
Sang-Keun Yoon (Daeduck Electronics Co., Ltd.)

### General Secretary

Jae Pil Jung (University of Seoul)  
Jun-Seok Ha (Chonnam National University)  
Kysik Shin (Korea Electronics Technology Institute)  
Jeong-Won Yoon (Korea Institute of Industrial Technology)

# ISMP 2015

<http://ismp2015.kmeps.or.kr>

14<sup>th</sup> International Symposium on Microelectronics and Packaging

October 13(Tue)-15(Thu), 2015 KINTEX Hall2, Seoul / Ilsan, Korea

## IMPORTANT DATES

Submission of Abstract : May 31, 2015  
Notification of Acceptance : July 15, 2015  
Pre-registration : August 15, 2015  
Submission of Final Manuscript : August 15, 2015  
Conference : October 13-15, 2015

Please submit the abstract through the email [kmeps@kmeps.or.kr](mailto:kmeps@kmeps.or.kr) and you can find your submission of you abstract at <http://ismp2015.kmeps.or.kr>

## REGISTRATION

Category	Pre-Registration		On-site Registration	
	Overseas	Domestic	Overseas	Domestic
Regular	USD 450	KRW 450,000	USD 550	KRW 550,000
Student	USD 200	KRW 200,000	USD 300	KRW 300,000
Banquet	USD 100 / KRW 100,000 (for student and accompanying person registration)			

\*\* Registration fee includes symposium program book with USB abstract proceeding, welcome party and luncheon coupons and free entrance ticket for the Korea Electronic Exhibition Show.

## WELCOME PARTY

DATE ; OCTOBER 13, 6 PM  
VENUE : KINTEX

## BANQUET

DATE ; OCTOBER 14, 6 PM  
VENUE : STANFORD HOTEL (<http://www.stanfordseoul.com/seoul>)

## ACCOMMODATIONS



**STANFORD HOTEL**

+82-2-6016-0001

<http://www.stanfordseoul.com>



**MVL HOTEL KINTEX**

+82-031-927-7700

<http://www.mvlhotel.com/kintex>



**PRESIDENT HOTEL**

+82-2-753-3131

<http://www.hotelpresident.co.kr>



**IBIS HOTEL**

+82-2-6272-1101

<https://ibis.ambatel.com>



**MARIGOLD HOTEL**

+82-2-326-5588

<http://www.hotelmargold.co.kr>

## CONTACT

Ms. So-Yoon Park (KMEPS)  
Tel : +82-2-538-0962, Fax : +82-2-538-0963  
E-mail : [kmeps@kmeps.or.kr](mailto:kmeps@kmeps.or.kr),  
<http://www.kmeps.or.kr>

## CONFERENCE LANGUAGE

The official language of the conference is English

# ISMP 2015

14<sup>th</sup> International Symposium on Microelectronics and Packaging

October 13(Tue)-15(Thu), 2015 KINTEX Hall2, Seoul / Ilsan, Korea

ISMP 2015 Venue (KINTEX) Daehwa-dong, Ilsanseo-gu, Goyang-si, Gyeonggi-do, <http://www.kintex.com>



The Korea International Exhibition Center (KINTEX) is a brand new convention center located within 45 minutes from Seoul's downtown and showcases heavy industry products. As the largest exhibition center in Korea, KINTEX offers 5 exhibition halls and 23 meeting rooms in the space of 53,975m<sup>2</sup>. Since its opening in April 2005, KINTEX has undergone the first of three expansion constructions, and is currently going through the second phase. When completed in September 2011, the expansion will add 53,975m<sup>2</sup> of exhibition space with world-class meeting facilities, placing KINTEX at the forefront of globalization and economic development in Korea.

## i-SEDEX 2015

International Semiconductor Exhibition

**OCTOBER 14-16**  
**KINTEX KOREA**



Device	Dram/Flash Memory, MCP, Memory module AP, MPU/MCU, DSP, DDI, PMIC, RFIC SoC etc. Foundries/Packaging Service, RFIDTag, Smart Card, Sensor, MEMS etc., Flat Panel Display (LCD, PDP, Organic EL, Etc)
Equipment Manufactures	Process Equipment, Assembly Equipment Test Equipment, Systems, SoC Test Systems etc. Inspection & Measurement Equipment General Equipment, Flat Panel Display Equipment
Factory Facility	Air Filtering, Clean Rooms, Flow Process Control, etc.
Materials	Materials of Assembly, Chemicals & Solids, Gases, FPD, Wafer Substrate
Components & Parts	Process Equipment, Sub System Parts
System & Software	FPGA/PLD, Wireless Communication, Interface Technology, Embedded Board Computer, CAD, Package Simulation, Test Program etc.

**CONTACT i-SEDEX**

[smpark@ksia.or.kr](mailto:smpark@ksia.or.kr) / +82-2-570-5275  
[www.sedex.org](http://www.sedex.org)